

RELIABILITY REPORT  
FOR  
MAX4467EKA+  
(MAX4465-MAX4469)  
PLASTIC ENCAPSULATED DEVICES

November 24, 2008

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
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<b>Approved by</b>
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## Conclusion

The MAX4467EKA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX4465-MAX4469 are micropower op amps optimized for use as microphone preamplifiers. They provide the ideal combination of an optimized gain bandwidth product vs. supply current, and low-voltage operation in an ultra-small package. The MAX4465/MAX4467/MAX4469 are unity-gain stable and deliver a 200kHz gain bandwidth from only 20 $\mu$ A of supply current. The MAX4466/MAX4468 are decompensated for a minimum stable gain of +5V/V and provide a 600kHz gain bandwidth product. In addition these amplifiers feature rail-to-rail outputs, high AVOL, plus excellent power-supply rejection and common-mode rejection ratios for operation in noisy environments. The MAX4467/MAX4468 include a complete shutdown mode. In shutdown, the amplifiers' supply current is reduced to 5nA and the bias current to the external microphone is cut off for ultimate power savings. The single MAX4465/MAX4466 are offered in the ultra-small 5-pin SC70 package, while the single with shutdown MAX4467/MAX4468 and dual MAX4469 are available in the space-saving 8-pin SOT23 package.

## II. Manufacturing Information

A. Description/Function:	Low-Cost, Micropower, SC70/SOT23-8, Microphone Preamplifiers with Complete Shutdown
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Texas E.
Assembly Location:	Carsem Malaysia
F. Date of Initial Production:	April 26, 2001

## III. Packaging Information

A. Package Type:	8-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-2501-0134
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	110°C/W
K. Single Layer Theta Jc:	80°C/W

## IV. Die Information

A. Dimensions:	65 X 24 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 44 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 24.4 \times 10^{-9}$$
$$\lambda = 24.4 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the B8 Process results in a FIT Rate of 2.71 @ 25C and 17.30 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The OX52 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX4467EKA+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	44	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data